

RTS 2005 Exhibitors (including Exhibitors of Poster Session)

Design and Fab less Zone
(LSI Design, System Design, Fabless)

Exploitation of Next Generation Co., Ltd. (ENG) (Japan) :

HITACHI ULSI Systems Co., Ltd. (Japan) :

Seireslabs Sdn Bhd (Malaysia) :

Toppan Technical Design Center Co., Ltd. (Japan)

Simulation Zone
(Design Tool, Simulation Tool)

AET Japan Inc. (Japan)

ATE Service Corporation (Japan) :

Cybernet Systems Co., Ltd. (Japan) : ANSYS

Fluent Asia Pacific Co., Ltd. (Japan) : epak, Icechip,

Keirex Technology Inc. (Japan) :

Moldflow Japan K.K. (Japan) : Moldflow MPI / Reactive Molding

Nagase Electronics Equipment Service Co., Ltd. (Japan) : 3D CAD system for DFM

IDM / Foundry Zone
(Wafer Process)

EPISIL Technologies Inc. (Taiwan) :

Powerchip Semiconductor Corporation PSC (Taiwan, Plan)

SAMSUNG Japan (Japan)

Toshiba Corporation Semiconductor Company (Japan, Plan)

Subcon Zone
(Packaging Process, JISSO, Module)

Casio Computer Co., Ltd. (Japan) :

Fukuryo Engineering (Japan) :

Hanwa Electric Ind., Co, Ltd. (Japan) :

Toshiba LSI Packaging Solutions Corporation (Japan)

Renesas Kyushu Semiconductor Corp. (Japan) :

SUNTEC Corporation (Japan) :

Testing Zone

(Wafer Test, Final Test, Test Engineering, Equipment and Material for Testing)

ALDETE Corporation (Japan) :

Apollowave Corporation (Japan) :

Elia Co., Ltd. (Japan) :

Genesis Technology Inc. (Japan, Plan)

King Yuan Electronics Co., Ltd. KYEC (Taiwan) :

STK Technology Co., Ltd. (Japan, Plan)

Tektronix Japan (Japan)

Yokogawa Electric Corporation (Japan)

PoP Zone

(Package on Package)

Amkor Technology Inc. (Korea)

Panasonic Factory Solutions Corporation PFSC (Japan)

SHARP Corporation (Japan)

Senjyu Metal Industry Co., Ltd. SMIC (Japan) :

Equipment Zone

(Equipment)

Hamamatsu photonics (Japan) :

Integrated Reliability Test Systems Inc. IRTS (U.S.A) : Highly Accelerated Thermal Shock (HATS) Test System

Manufacturing Integration Technology Ltd. MIT (Singapore) :

Nikon Instech Co., Ltd. (Japan) :

Malcom Co., Ltd.(Japan) :

Substrate Zone

(Substrate)

Hano Seisakusho Co., Ltd. (Japan) :
Hirai Seimitsu Kogyo Corporation (Japan) :
Ibitec (Japan) : Integration, Consulting, DFM
Japan Circuit IndustrialCo., Ltd. (Japan) :
Nippon Graphite Industry (Japan) :
Nihonmicron Ltd. (Japan)
Oki Printed Circuit Co., Ltd. (Japan) :

Distributor and Information Zone
(Agent, Distributor, Consultant, Government):

Harada Corporation (Japan) :
Inoueki Co., Ltd. (Japan) : Highly Accelerated Thermal Shock (HATS) Test System
Marubun Corporation (Japan) :
MIDA (Malaysia)
Minami Co., Ltd. (Japan) :
Sino-Japan Microelectronic Industry Center for Incubation (China) :